

## 双频电压控制晶体振荡器 (VCXO) ( 100 kHz 至 250 MHz )

### 特性

- 支持 100 kHz 至 250 MHz 之间的任意频率
- 两个可选输出频率
- 低抖动操作
- 交付周期短: <2 周
- AT 切割基础模式晶体确保高可靠性 / 低老化
- 高电源噪声抑制
- 1% 的控制电压线性度
- 提供 CMOS、LVPECL、LVDS 和 HCSL 输出
- 可选 1:2 CMOS 扇出缓冲器
- 3.3 和 2.5 V 电源选项
- 符合行业标准的 5x7、3.2x5 和 2.5x3.2 毫米封装
- 无铅 / 符合 RoHS
- 可选 Kv ( 60、90、120、150 ppm/V )

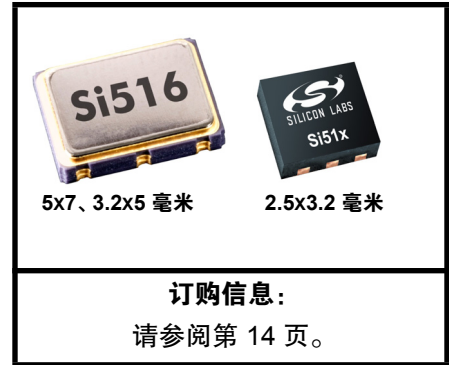
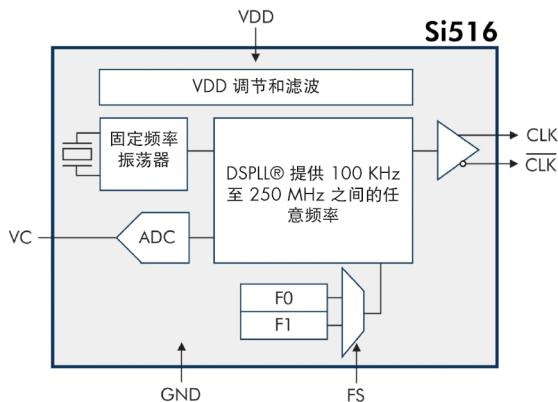
### 应用

- SONET/SDH/OTN
- PON
- 低抖动 PLL
- xDSL
- 广播电视
- 电信
- 交换机 / 路由器
- FPGA/ASIC 时钟脉冲振荡

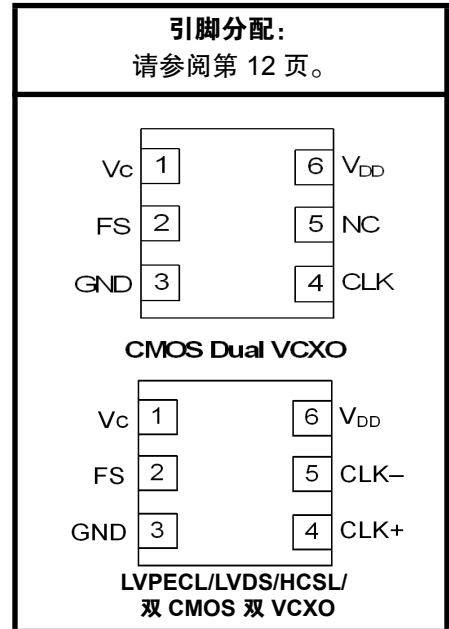
### 说明

Si516 双频 VCXO 采用 Silicon Laboratories 先进的 PLL 技术, 可提供 100 kHz 至 250 MHz 之间的任意频率。不同于传统 VCXO 对于各个输出频率都需要使用不同的晶体, Si516 使用一个固定晶体以及 Silicon Labs 专有的合成器, 可生成此范围内的任意频率。借助这个基于 IC 的方法, 晶体谐振器的可靠性、机械强度和稳定性都将得到提高。此外, 该解决方案提供出色的控制电压线性度和电源噪声抑制能力, 提高了 PLL 稳定性, 并简化了噪声环境中的低抖动 PLL 设计。可针对各种各样的用户规格要求在工厂内对 Si516 进行配置, 包括频率、电源电压、输出格式、调谐坡度和稳定性。特殊配置在发货时由工厂编程, 从而免除了定制频率振荡器导致的长交付周期和非经常性工程费用。

### 功能方框图



**订购信息:**  
请参阅第 14 页。



## TABLE OF CONTENTS

---

<u>Section</u>	<u>Page</u>
1. Electrical Specifications .....	3
2. Solder Reflow and Rework Requirements for 2.5x3.2 mm Packages .....	11
3. Pin Descriptions .....	12
3.1. Dual CMOS Buffer .....	13
4. Ordering Information .....	14
5. Package Outline Diagram: 5 x 7 mm, 6-pin .....	15
6. PCB Land Pattern: 5 x 7 mm, 6-pin .....	16
7. Package Outline Diagram: 3.2 x 5.0 mm, 6-pin .....	17
8. PCB Land Pattern: 3.2 x 5.0 mm, 6-pin .....	18
9. Package Outline Diagram: 2.5 x 3.2 mm, 6-pin .....	19
10. PCB Land Pattern: 2.5 x 3.2 mm, 6-pin .....	21
11. Top Marking .....	22
11.1. Si516 Top Marking .....	22
11.2. Top Marking Explanation .....	22
Document Change List .....	23

## 1. Electrical Specifications

**Table 1. Recommended Operating Conditions**

$V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply Voltage	$V_{DD}$	3.3 V option	2.97	3.3	3.63	V
		2.5 V option	2.25	2.5	2.75	V
Supply Current	$I_{DD}$	CMOS, 100 kHz, single-ended	—	24	29	mA
		LVDS (output enabled)	—	22	26	mA
		LVPECL (output enabled)	—	42	46	mA
		HCSL (output enabled)	—	44	47	mA
		Tristate (output disabled)	—	—	22	mA
FS "1" Setting	$V_{IH}$		$0.80 \times V_{DD}$	—	—	V
FS "0" Setting	$V_{IL}$		—	—	$0.20 \times V_{DD}$	V
FS Internal Pull-Up Resistor	$R_I$		—	45	—	k $\Omega$
Operating Temperature	$T_A$		-40	—	85	°C

**Table 2. Vc Control Voltage Input**

$V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Control Voltage Range	$V_C$		$0.1 \times V_{DD}$	$V_{DD}/2$	$0.9 \times V_{DD}$	V
Control Voltage Tuning Slope (10 to 90% $V_{DD}$ )	Kv	Ordering option	60, 90, 120, 150			ppm/V
Kv Variation	Kv_var		—	—	$\pm 10$	%
Control Voltage Linearity	$L_{VC}$	BSL	-5	$\pm 1$	+5	%
Modulation Bandwidth	BW		—	10	—	kHz
Vc Input Impedance	$Z_{VC}$		—	100	—	k $\Omega$

**Table 3. Output Clock Frequency Characteristics**

$V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Nominal Frequency	$F_O$	CMOS, Dual CMOS	0.1	—	212.5	MHz
	$F_O$	LVDS/LVPECL/HCSL	0.1	—	250	MHz
Temperature Stability	$S_T$	$T_A = -40$ to $+85$ °C	-20	—	+20	ppm
Aging	A	Frequency drift over 10-year life	—	—	$\pm 8.5$	ppm
Minimum Absolute Pull Range	APR	Ordering option	$\pm 30, \pm 50, \pm 80, \pm 100$			ppm
Startup Time	$T_{SU}$	Minimum $V_{DD}$ until output frequency ( $F_O$ ) within specification	—	—	10	ms
Disable Time	$T_D$	$F_O \geq 10$ MHz	—	—	5	$\mu$ s
		$F_O < 10$ MHz	—	—	40	$\mu$ s
Enable Time	$T_D$	$F_O \geq 10$ MHz	—	—	20	$\mu$ s
		$F_O < 10$ MHz	—	—	60	$\mu$ s
Settling Time after FS Change	$t_{FRQ}$		—	—	10	ms

**Table 4. Output Clock Levels and Symmetry** $V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
CMOS Output Logic High	$V_{OH}$		$0.85 \times V_{DD}$	—	—	V
CMOS Output Logic Low	$V_{OL}$		—	—	$0.15 \times V_{DD}$	V
CMOS Output Logic High Drive	$I_{OH}$	3.3 V	-8	—	—	mA
		2.5 V	-6	—	—	mA
CMOS Output Logic Low Drive	$I_{OL}$	3.3 V	8	—	—	mA
		2.5 V	6	—	—	mA
CMOS Output Rise/Fall Time (20 to 80% $V_{DD}$ )	$T_R/T_F$	0.1 to 125 MHz, $C_L = 15$ pF	—	0.8	1.2	ns
		0.1 to 212.5 MHz, $C_L =$ no load	—	0.6	0.9	ns
LVPECL/HCSL Output Rise/Fall Time (20 to 80% $V_{DD}$ )	$T_R/T_F$		—	—	565	ps
LVDS Output Rise/Fall Time (20 to 80% $V_{DD}$ )	$T_R/T_F$		—	—	800	ps
LVPECL Output Common Mode	$V_{OC}$	$50 \Omega$ to $V_{DD} - 2$ V, single-ended	—	$V_{DD} - 1.4$ V	—	V
LVPECL Output Swing	$V_O$	$50 \Omega$ to $V_{DD} - 2$ V, single-ended	0.55	0.8	0.90	$V_{PPSE}$
LVDS Output Common Mode	$V_{OC}$	$100 \Omega$ line-line, $V_{DD} = 3.3/2.5$ V	1.13	1.23	1.33	V
LVDS Output Swing	$V_O$	Single-ended $100 \Omega$ differential termination	0.25	0.38	0.42	$V_{PPSE}$
HCSL Output Common Mode	$V_{OC}$	$50 \Omega$ to ground	0.35	0.38	0.42	V
HCSL Output Swing	$V_O$	Single-ended	0.58	0.73	0.85	$V_{PPSE}$
Duty Cycle	DC		48	50	52	%

**Table 5. Output Clock Jitter and Phase Noise (LVPECL)**

$V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C; Output Format = LVPECL

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Period Jitter (RMS)	$J_{PRMS}$	10 k samples <sup>1</sup>	—	—	1.3	ps
Period Jitter (PK-PK)	$J_{PPKPK}$	10 k samples <sup>1</sup> (brickwall)	—	—	11	ps
Phase Jitter (RMS)	$\phi J$	12 kHz to 20 MHz <sup>2</sup> (brickwall)	—	0.9	1.3	ps
		1.875 MHz to 20 MHz <sup>2</sup> (brickwall)	—	0.25	0.5	ps
Phase Noise, 155.52 MHz	$\phi N$	100 Hz offset	—	-71	—	dBc/Hz
		1 kHz offset	—	-94	—	dBc/Hz
		10 kHz offset	—	-113	—	dBc/Hz
		100 kHz offset	—	-124	—	dBc/Hz
		1 MHz offset	—	-136	—	dBc/Hz
Additive RMS Jitter Due to External Power Supply Noise <sup>3</sup>	$J_{PSRR}$	100 kHz sinusoidal noise	—	4.0	—	ps
		200 kHz sinusoidal noise	—	3.5	—	ps
		500 kHz sinusoidal noise	—	3.5	—	ps
		1 MHz sinusoidal noise	—	3.5	—	ps
Spurious Performance	SPR	$F_O = 156.25$ MHz, Offset > 10 kHz	—	-75	—	dBc

**Notes:**

1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.
3. 156.25 MHz. Increase in jitter on output clock due to spurs introduced by sinewave noise added to VDD (100 mV<sub>PP</sub>).

**Table 6. Output Clock Jitter and Phase Noise (LVDS)**

$V_{DD} = 1.8 \text{ V} \pm 5\%$ , 2.5 or 3.3 V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C; Output Format = LVDS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Period Jitter (RMS)	JPRMS	10k samples <sup>1</sup>	—	—	2.1	ps
Period Jitter (Pk-Pk)	JPPKPK	10k samples <sup>1</sup>	—	—	18	ps
Phase Jitter (RMS)	$\phi J$	1.875 MHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.25	0.55	ps
		12 kHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.8	1.1	ps
Phase Noise, 156.25 MHz	$\phi N$	100 Hz	—	-72	—	dBc/Hz
		1 kHz	—	-93	—	dBc/Hz
		10 kHz	—	-114	—	dBc/Hz
		100 kHz	—	-123	—	dBc/Hz
		1 MHz	—	-136	—	dBc/Hz
Spurious	SPR	LVPECL output, 156.25 MHz, offset > 10 kHz	—	-75	—	dBc
<b>Notes:</b>						
1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.						
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 and 250 MHz.						

**Table 7. Output Clock Jitter and Phase Noise (HCSL)**

$V_{DD} = 1.8\text{ V} \pm 5\%$ , 2.5 or 3.3 V  $\pm 10\%$ ,  $T_A = -40$  to  $+85\text{ }^\circ\text{C}$ ; Output Format = HCSL

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Period Jitter (RMS)	JPRMS	10k samples*	—	—	1.2	ps
Period Jitter (Pk-Pk)	JPPKPK	10k samples*	—	—	11	ps
Phase Jitter (RMS)	$\phi J$	1.875 MHz to 20 MHz integration bandwidth* (brickwall)	—	0.25	0.30	ps
		12 kHz to 20 MHz integration bandwidth* (brickwall)	—	0.8	1.0	ps
Phase Noise, 156.25 MHz	$\phi N$	100 Hz	—	-75	—	dBc/Hz
		1 kHz	—	-98	—	dBc/Hz
		10 kHz	—	-117	—	dBc/Hz
		100 kHz	—	-127	—	dBc/Hz
		1 MHz	—	-136	—	dBc/Hz
Spurious	SPR	LVPECL output, 156.25 MHz, offset > 10 kHz	—	-75	—	dBc

**\*Note:** Applies to an output frequency of 100 MHz.



**Table 8. Output Clock Jitter and Phase Noise (CMOS, Dual CMOS)**

$V_{DD} = 1.8\text{ V} \pm 5\%$ , 2.5 or 3.3 V  $\pm 10\%$ ,  $T_A = -40$  to  $+85\text{ }^\circ\text{C}$ ; Output Format = CMOS, Dual CMOS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Phase Jitter (RMS)	$\phi_J$	1.875 MHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.25	0.35	ps
		12 kHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.8	1.1	ps
Phase Noise, 156.25 MHz	$\phi_N$	100 Hz	—	-71	—	dBc/Hz
		1 kHz	—	-93	—	dBc/Hz
		10 kHz	—	-113	—	dBc/Hz
		100 kHz	—	-123	—	dBc/Hz
		1 MHz	—	-136	—	dBc/Hz
Spurious	SPR	LVPECL output, 156.25 MHz, offset > 10 kHz	—	-75	—	dBc

**Notes:**

1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 MHz.
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 MHz.

**Table 9. Environmental Compliance and Package Information**

Parameter	Conditions/Test Method
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Contact Pads	Gold over Nickel

**Table 10. Thermal Characteristics**

Parameter	Symbol	Test Condition	Value	Unit
CLCC, Thermal Resistance Junction to Ambient	$\theta_{JA}$	Still air	110	°C/W
2.5x3.2mm, Thermal Resistance Junction to Ambient	$\theta_{JA}$	Still air	164	°C/W

**Table 11. Absolute Maximum Ratings<sup>1</sup>**

Parameter	Symbol	Rating	Unit
Maximum Operating Temperature	$T_{AMAX}$	85	°C
Storage Temperature	$T_S$	-55 to +125	°C
Supply Voltage	$V_{DD}$	-0.5 to +3.8	V
Input Voltage (any input pin)	$V_I$	-0.5 to $V_{DD} + 0.3$	V
ESD Sensitivity (HBM, per JESD22-A114)	HBM	2	kV
Soldering Temperature (Pb-free profile) <sup>2</sup>	$T_{PEAK}$	260	°C
Soldering Temperature Time at $T_{PEAK}$ (Pb-free profile) <sup>2</sup>	$T_P$	20–40	sec

**Notes:**

1. Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation or specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. The device is compliant with JEDEC J-STD-020E.

## **2. Solder Reflow and Rework Requirements for 2.5x3.2 mm Packages**

Reflow of Silicon Labs' components should be done in a manner consistent with the IPC/JEDEC J-STD-20E standard. The temperature of the package is not to exceed the classification Temperature provided in the standard. The part should not be within -5°C of the classification or peak reflow temperature ( $T_{PEAK}$ ) for longer than 30 seconds. Key to maintaining the integrity of the component is providing uniform heating and cooling of the part during reflow and rework. Uniform heating is achieved through having a preheat soak and controlling the temperature ramps in the process. J-STD-20E provides minimum and maximum temperatures and times for the preheat/Soak step that need to be followed, even for rework. The entire assembly area should be heated during rework. Hot air should be flowed from both the bottom of the board and the top of the component. Heating from the top only will cause un-even heating of component and can lead to part integrity issues. Temperature Ramp-up rate are not to exceed 3°C/second. Temperature ramp-down rates from peak to final temperature are not to exceed 6°C/second. Time from 25°C to peak temperature is not to exceed 8 min for Pb-free solders.

## 3. Pin Descriptions



**Table 12. Si516 Pin Descriptions (CMOS)**

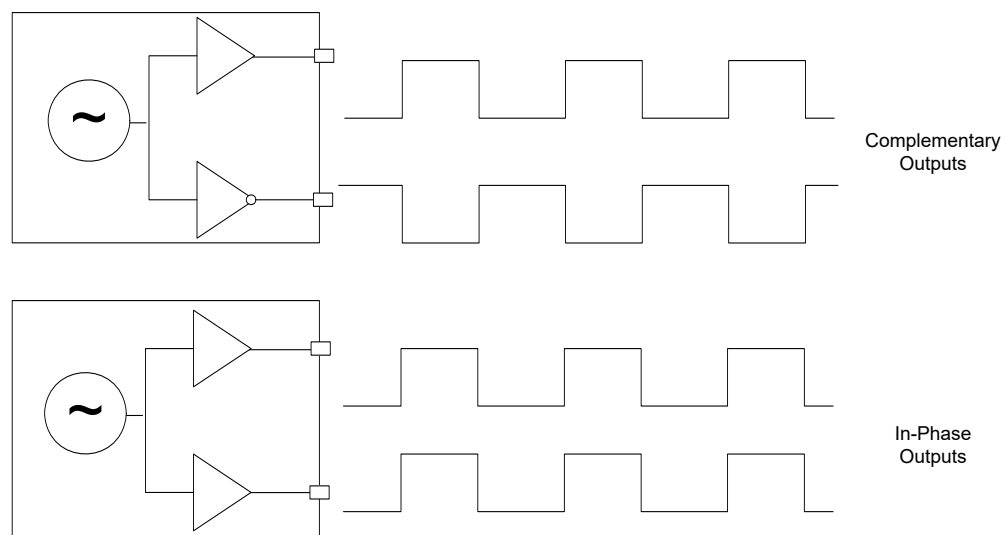
Pin	Name	CMOS Function
1	V <sub>C</sub>	Control Voltage Input.
2	FS	Frequency Select. 0 = First frequency selected. 1 = Second frequency selected.
3	GND	Electrical and Case Ground.
4	CLK	Clock Output.
5	NC	No connect. Make no external connection to this pin.
6	V <sub>DD</sub>	Power Supply Voltage.

**Table 13. Si516 Pin Descriptions (LVPECL/LVDS/HCSL/Dual CMOS)**

Pin	Name	LVPECL/LVDS/HCSL/Dual CMOS Function
1	V <sub>C</sub>	Control Voltage Input.
2	FS	Frequency Select. 0 = First frequency selected. 1 = Second frequency selected.
3	GND	Electrical and Case Ground.
4	CLK+	Clock Output.
5	CLK-	Complementary Clock Output.
6	V <sub>DD</sub>	Power Supply Voltage.

### 3.1. Dual CMOS Buffer

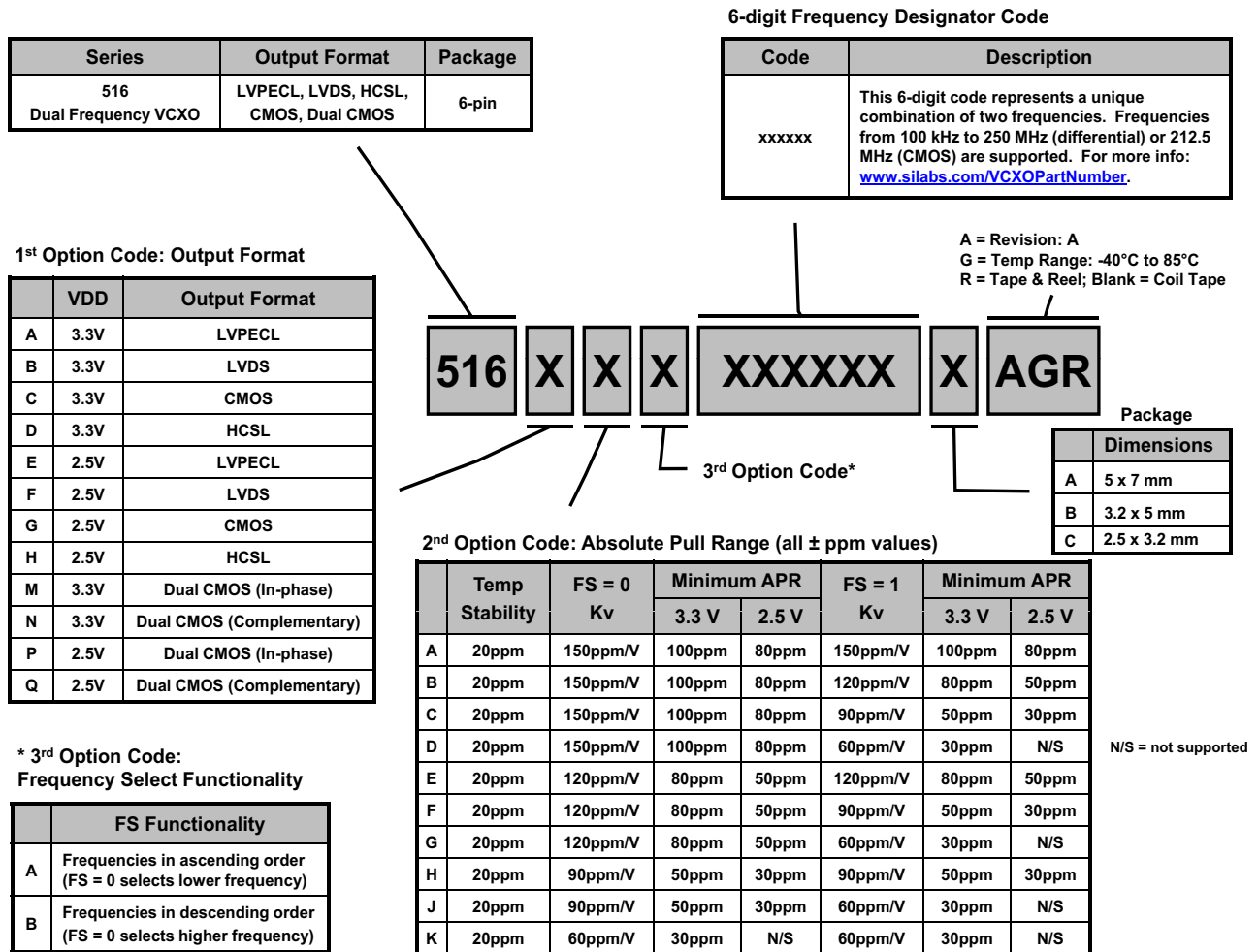
Dual CMOS output format ordering options support either complementary or in-phase output signals. This feature enables replacement of multiple VCXOs with a single Si516 device.



**Figure 1. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Output**

## 4. Ordering Information

The Si516 supports a variety of options including frequency, minimum absolute pull range (APR), tuning slope, output format, and  $V_{DD}$ . Specific device configurations are programmed into the Si516 at time of shipment. Configurations are specified using the Part Number Configuration chart shown below. Silicon Labs provides a web browser-based part number configuration utility to simplify this process. To access this tool refer to [www.silabs.com/oscillators](http://www.silabs.com/oscillators) and click “Customize” in the product table. The Si516 VCXO series is supplied in industry-standard, RoHS compliant, lead-free, 2.5 x 3.2 mm, 3.2 x 5.0 mm, and 5 x 7 mm packages. Tape and reel packaging is an ordering option.



**Figure 2. Part Number Convention**

Example ordering part number: 516AAB000213AAG.

The series prefix, 516, indicates the device is a dual frequency VCXO.

The 1st option code A specifies the output format is LVPECL and powered from a 3.3 V supply. The Absolute Pull Range code A indicates a temperature stability of  $\pm 20$  ppm with a tuning slope of  $\pm 150$  ppm/V. The 3rd option code B specifies the frequencies are listed in descending order and FS = 0 selects the higher frequency.

The frequency code is 000213. Per this convention, and as indicated by the part number lookup utility at [www.silabs.com/VCXOPartNumber](http://www.silabs.com/VCXOPartNumber), the two output frequencies are 156.25 MHz and 125 MHz. The package code A refers to the 5 x 7 mm footprint with six pins. The last A refers to the product revision, G indicates the temperature range (-40 to +85 °C), and R specifies the device ships in tape and reel format.

## 5. Package Outline Diagram: 5 x 7 mm, 6-pin

Figure 3 illustrates the package details for the Si516. Table 14 lists the values for the dimensions shown in the illustration.

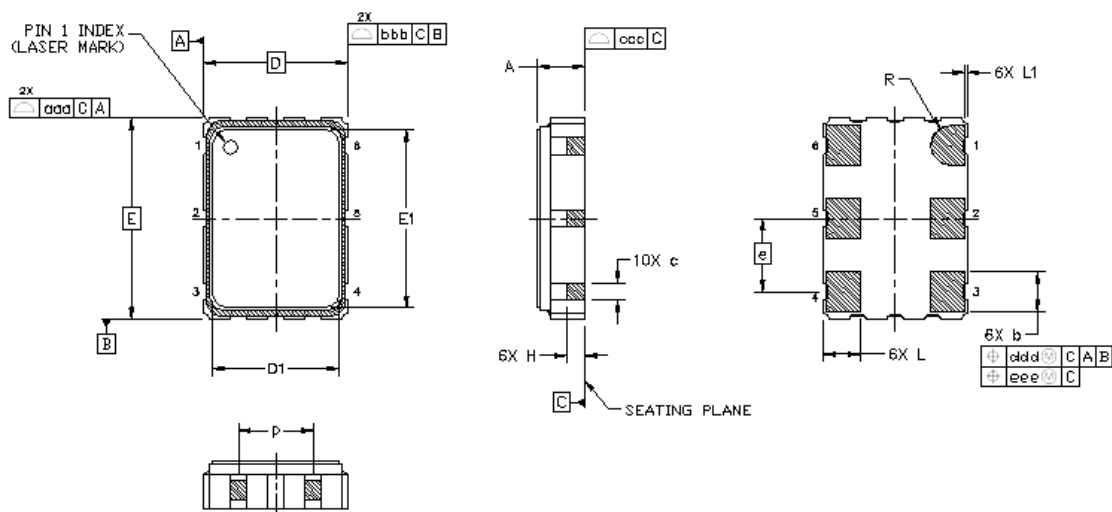


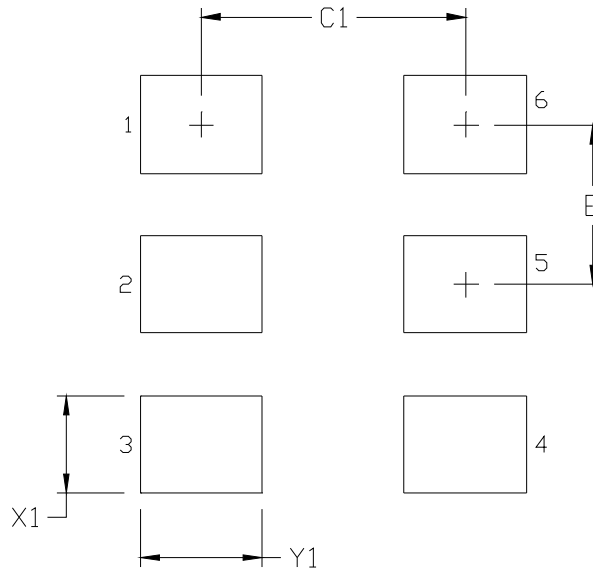
Figure 3. Si516 Outline Diagram

Table 14. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	1.50	1.65	1.80
b	1.30	1.40	1.50
c	0.50	0.60	0.70
D	5.00 BSC		
D1	4.30	4.40	4.50
e	2.54 BSC		
E	7.00 BSC		
E1	6.10	6.20	6.30
H	0.55	0.65	0.75
L	1.17	1.27	1.37
L1	0.05	0.10	0.15
p	1.80	—	2.60
R	0.70 REF		
aaa	0.15		
bbb	0.15		
ccc	0.10		
ddd	0.10		
eee	0.05		
<b>Notes:</b>			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			

## 6. PCB Land Pattern: 5 x 7 mm, 6-pin

Figure 4 illustrates the 5 x 7 mm PCB land pattern for the Si516. Table 15 lists the values for the dimensions shown in the illustration.



**Figure 4. Si516 PCB Land Pattern**

**Table 15. PCB Land Pattern Dimensions (mm)**

Dimension	(mm)
C1	4.20
E	2.54
X1	1.55
Y1	1.95

**Notes:**

**General**

- All dimensions shown are in millimeters (mm) unless otherwise noted.
- Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- This Land Pattern Design is based on the IPC-7351 guidelines.
- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

**Solder Mask Design**

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu\text{m}$  minimum, all the way around the pad.

**Stencil Design**

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1.

**Card Assembly**

- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.



## 7. Package Outline Diagram: 3.2 x 5.0 mm, 6-pin

Figure illustrates the package details for the 3.2 x 5 mm Si516. Table 16 lists the values for the dimensions shown in the illustration.

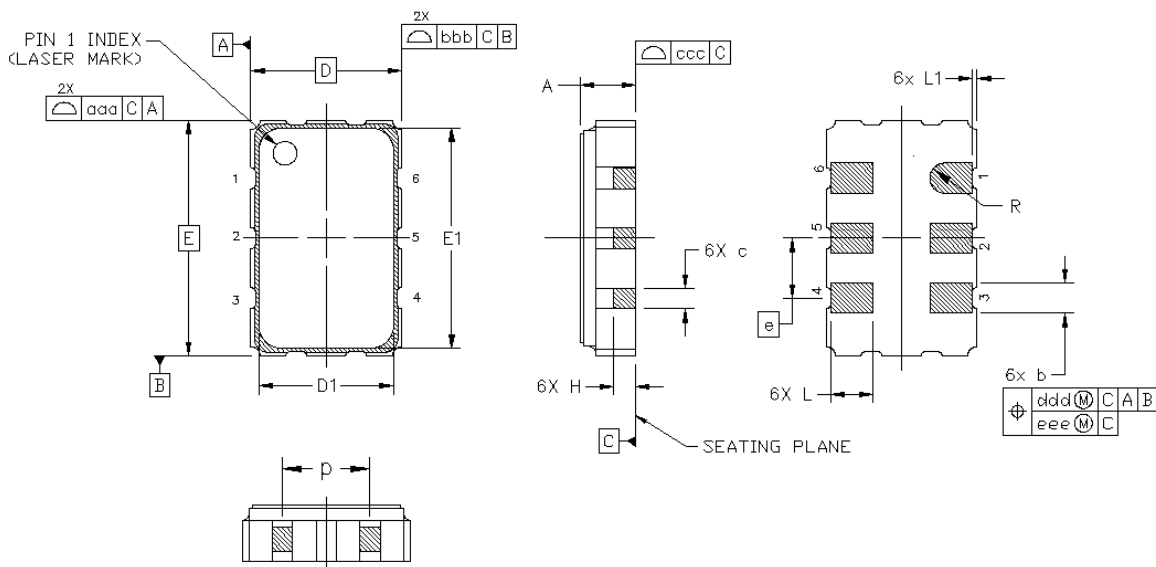


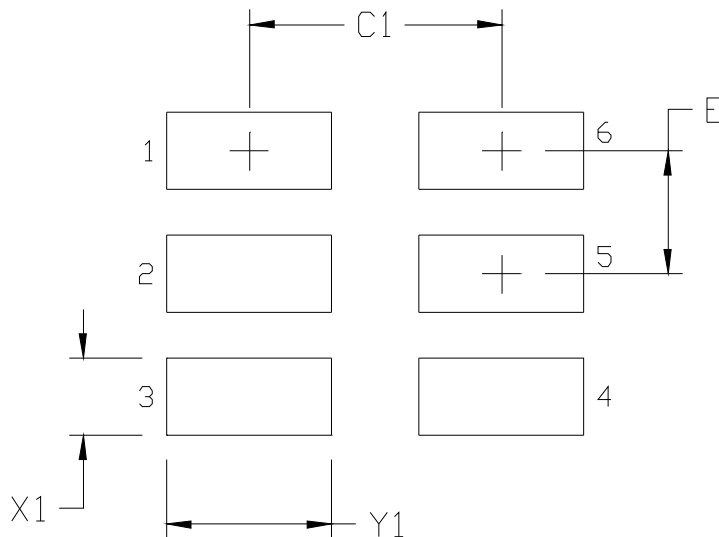
Figure 5. Si516 Outline Diagram

Table 16. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	1.06	1.17	1.33
b	0.54	0.64	0.74
c	0.35	0.45	0.55
D	3.20 BSC		
D1	2.55	2.60	2.65
e	1.27 BSC		
E	5.00 BSC		
E1	4.35	4.40	4.45
H	0.45	0.55	0.65
L	0.80	0.90	1.00
L1	0.05	0.10	0.15
p	1.17	1.27	1.37
R	0.32 REF		
aaa	0.15		
bbb	0.15		
ccc	0.10		
ddd	0.10		
eee	0.05		
<b>Notes:</b>			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			

## 8. PCB Land Pattern: 3.2 x 5.0 mm, 6-pin

Figure 6 illustrates the recommended 3.2 x 5.0 mm PCB land pattern for the Si516. Table 17 lists the values for the dimensions shown in the illustration.



**Figure 6. Si516 PCB Land Pattern**

**Table 17. PCB Land Pattern Dimensions (mm)**

Dimension	(mm)
C1	2.60
E	1.27
X1	0.80
Y1	1.70

**Notes:**

**General**

- All dimensions shown are in millimeters (mm) unless otherwise noted.
- Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- This Land Pattern Design is based on the IPC-7351 guidelines.
- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

**Solder Mask Design**

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

**Stencil Design**

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1.

**Card Assembly**

- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

## 9. Package Outline Diagram: 2.5 x 3.2 mm, 6-pin

Figure 7 illustrates the package details for the 2.5 x 3.2 mm Si516. Table 18 lists the values for the dimensions shown in the illustration.



Figure 7. Si516 Outline Diagram

**Table 18. Package Diagram Dimensions (mm)**

<b>Dimension</b>	<b>Min</b>	<b>Nom</b>	<b>Max</b>
A	—	—	1.1
A1	0.26 REF		
A2	0.7 REF		
W	0.65	0.7	0.75
D	3.20 BSC		
e	1.25 BSC		
E	2.50 BSC		
M	0.30 BSC		
L	0.45	0.5	0.55
D1	2.5 BSC		
E1	1.65 BSC		
SE	0.825 BSC		
aaa	0.1		
bbb	0.2		
ddd	0.08		
<b>Notes:</b>			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			

## 10. PCB Land Pattern: 2.5 x 3.2 mm, 6-pin

Figure 8 illustrates the 2.5 x 3.2 mm PCB land pattern for the Si516. Table 19 lists the values for the dimensions shown in the illustration.

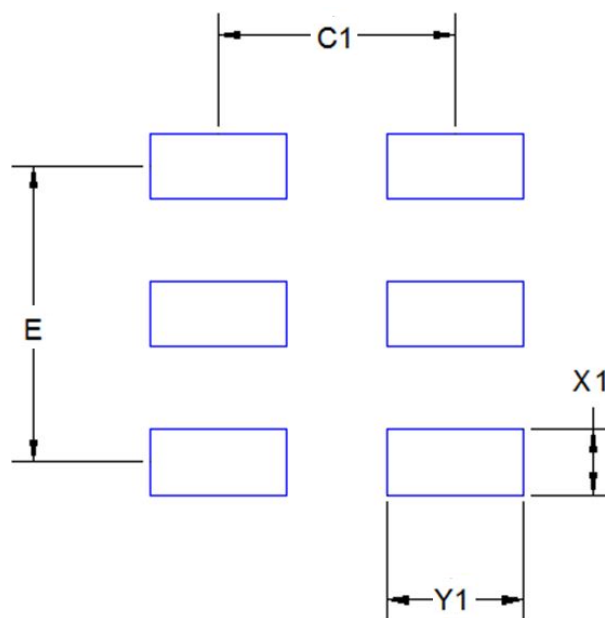


Figure 8. Si516 Recommended PCB Land Pattern

Table 19. PCB Land Pattern Dimensions (mm)

Dimension	(mm)
C1	1.9
E	2.50
X1	0.70
Y1	1.05

**Notes:**

**General**

- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.
- This Land Pattern Design is based on the IPC-7351 guidelines.

**Solder Mask Design**

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu\text{m}$  minimum, all the way around the pad.

**Stencil Design**

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pins.

**Card Assembly**

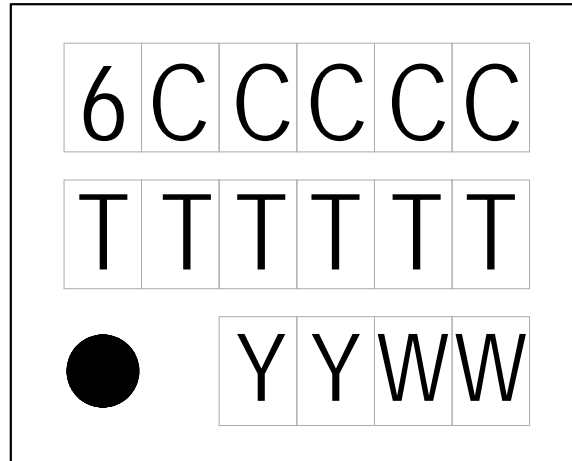
- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

# Si516

## 11. Top Marking

Use the part number configuration utility located at: [www.silabs.com/VCXOPartNumber](http://www.silabs.com/VCXOPartNumber) to cross-reference the mark code to a specific device configuration.

### 11.1. Si516 Top Marking



### 11.2. Top Marking Explanation

<b>Mark Method:</b>	Laser	
<b>Line 1 Marking:</b>	6 = Si516 CCCCC = Mark Code	6CCCCC
<b>Line 2 Marking:</b>	TTTTTT = Assembly Manufacturing Code	TTTTTT
<b>Line 3 Marking:</b>	Pin 1 indicator.	Circle with 0.5 mm diameter; left-justified
	YY = Year. WW = Work week. Characters correspond to the year and work week of package assembly.	YYWW

## REVISION HISTORY

### Revision 1.2

June, 2018

- Changed “Trays” to “Coil Tape” in Ordering Guide.

### Revision 1.1

December, 2017

- Added 2.5 x 3.2 mm package.

### Revision 1.0

- Updated Table 1 on page 3.
  - Updates to supply current typical and maximum values for CMOS, LVDS, LVPECL and HCSL.
  - CMOS frequency test condition corrected to 100 MHz.
  - Updates to OE VIH minimum and VIL maximum values.
- Updated Table 3 on page 4.
  - Dual CMOS nominal frequency maximum added.
  - Disable time maximum values updated.
  - Enable time parameter added.
- Updated Table 4 on page 5.
  - CMOS output rise / fall time typical and maximum values updated.
  - LVPECL/HCSL output rise / fall time maximum value updated.
  - LVPECL output swing maximum value updated.
  - LVDS output common mode typical and maximum values updated.
  - HCSL output swing maximum value updated.
  - Duty cycle minimum and maximum values tightened to 48/52%.
- Updated Table 5 on page 6.
  - Phase jitter test condition, typical and maximum value updated.
  - Phase noise typical values updated.
  - Additive RMS jitter due to external power supply noise typical values updated.
- Added Tables 6, 7, 8 for LVDS, HCSL, CMOS and Dual CMOS operations.
- Added note to Figure 2 clarifying CMOS and Dual CMOS maximum frequency.
- Updated Figure outline diagram to correct pinout.
- Updated “11. Top Marking” section and moved to page 22.



## ClockBuilder Pro

One-click access to Timing tools, documentation, software, source code libraries & more. Available for Windows and iOS (CBGo only).

[www.silabs.com/CBPro](http://www.silabs.com/CBPro)



**Timing Portfolio**  
[www.silabs.com/timing](http://www.silabs.com/timing)



**SW/HW**  
[www.silabs.com/CBPro](http://www.silabs.com/CBPro)



**Quality**  
[www.silabs.com/quality](http://www.silabs.com/quality)



**Support and Community**  
[community.silabs.com](http://community.silabs.com)

### Disclaimer

Silicon Labs intends to provide customers with the latest, accurate, and in-depth documentation of all peripherals and modules available for system and software implementers using or intending to use the Silicon Labs products. Characterization data, available modules and peripherals, memory sizes and memory addresses refer to each specific device, and "Typical" parameters provided can and do vary in different applications. Application examples described herein are for illustrative purposes only. Silicon Labs reserves the right to make changes without further notice and limitation to product information, specifications, and descriptions herein, and does not give warranties as to the accuracy or completeness of the included information. Silicon Labs shall have no liability for the consequences of use of the information supplied herein. This document does not imply or express copyright licenses granted hereunder to design or fabricate any integrated circuits. The products are not designed or authorized to be used within any Life Support System without the specific written consent of Silicon Labs. A "Life Support System" is any product or system intended to support or sustain life and/or health, which, if it fails, can be reasonably expected to result in significant personal injury or death. Silicon Labs products are not designed or authorized for military applications. Silicon Labs products shall under no circumstances be used in weapons of mass destruction including (but not limited to) nuclear, biological or chemical weapons, or missiles capable of delivering such weapons.

### Trademark Information

Silicon Laboratories Inc.®, Silicon Laboratories®, Silicon Labs®, SiLabs® and the Silicon Labs logo®, Bluegiga®, Bluegiga Logo®, Clockbuilder®, CMEMS®, DSPLL®, EFM®, EFM32®, EFR, Ember®, Energy Micro, Energy Micro logo and combinations thereof, "the world's most energy friendly microcontrollers", Ember®, EZLink®, EZRadio®, EZRadioPRO®, Gecko®, ISOModem®, Micrium, Precision32®, ProSLIC®, Simplicity Studio®, SiPHY®, Telegesis, the Telegesis Logo®, USBXpress®, Zentri, Z-Wave, and others are trademarks or registered trademarks of Silicon Labs. ARM, CORTEX, Cortex-M3 and THUMB are trademarks or registered trademarks of ARM Holdings. Keil is a registered trademark of ARM Limited. All other products or brand names mentioned herein are trademarks of their respective holders.



Silicon Laboratories Inc.  
400 West Cesar Chavez  
Austin, TX 78701  
USA

<http://www.silabs.com>